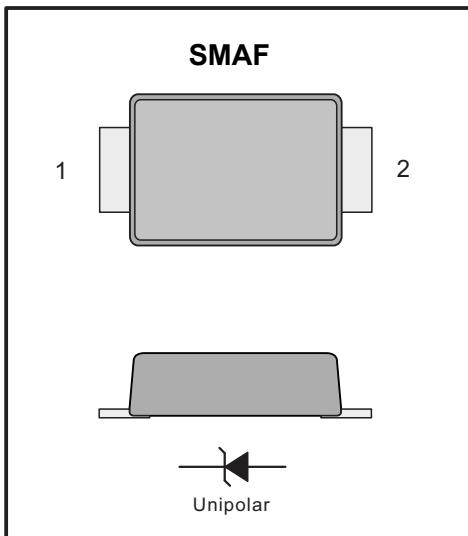


### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



### FEATURES

- ◆ Metal silicon junction, majority carrier conduction
- ◆ For surface mounted applications
- ◆ Low power loss, high efficiency
- ◆ High forward surge current capability
- ◆ For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

### MECHANICAL DATA

- ◆ Case: SMAF
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 27mg / 0.00095oz

### Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

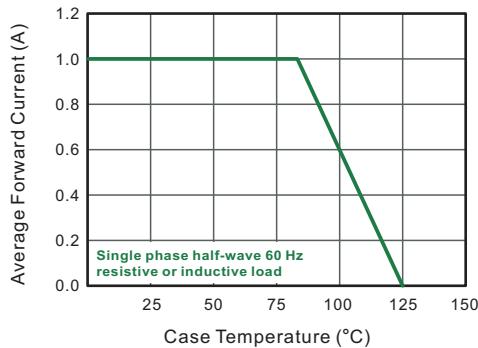
Parameter	Symbols	SS12F	SS14F	SS16F	SS18F	SS110F	SS112F	SS115F	SS120F	Units					
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	20	40	60	80	100	120	150	200	V					
Maximum RMS voltage	$V_{RMS}$	14	28	42	56	70	84	105	140	V					
Maximum DC Blocking Voltage	$V_{DC}$	20	40	60	80	100	120	150	200	V					
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0							A						
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	30							A						
Max Instantaneous Forward Voltage at 1 A	$V_F$	0.55		0.70		0.85		0.90		V					
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Reverse Voltage $T_a = 100^\circ\text{C}$	$I_R$	0.3 10			0.2 5			0.1 2		mA					
Typical Junction Capacitance <sup>(1)</sup>	$C_j$	110		80											
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$	95							$^\circ\text{C}/\text{W}$						
Operating Junction Temperature Range	$T_j$	-55 ~ +125							$^\circ\text{C}$						
Storage Temperature Range	$T_{stg}$	-55 ~ +150							$^\circ\text{C}$						

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C.

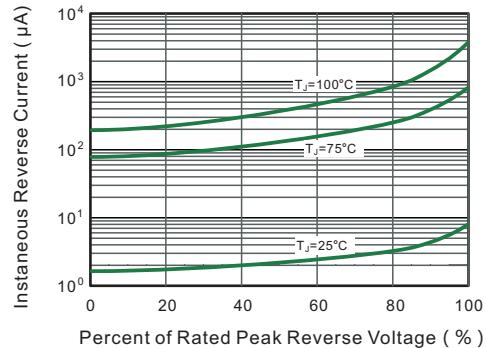
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

## Typical Characteristics

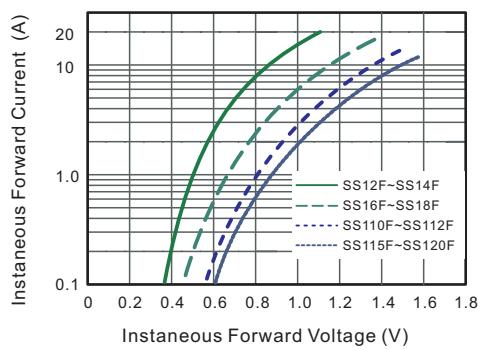
**Fig.1 Forward Current Derating Curve**



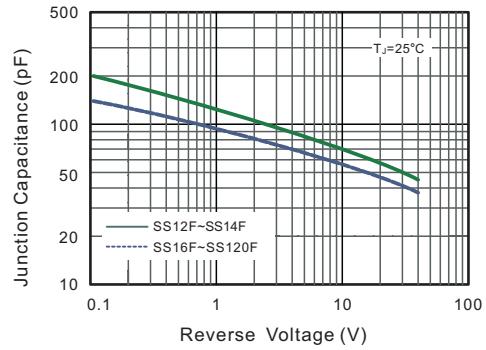
**Fig.2 Typical Reverse Characteristics**



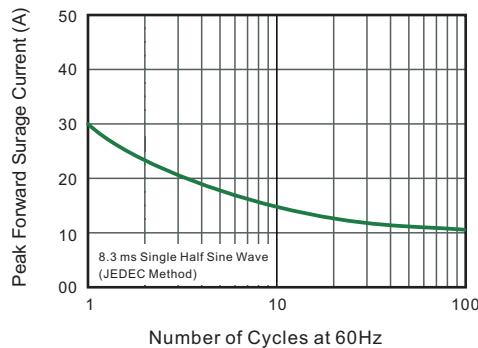
**Fig.3 Typical Forward Characteristic**



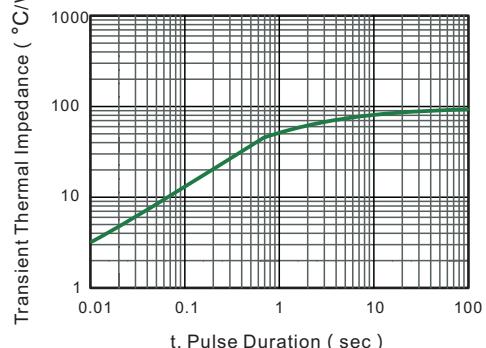
**Fig.4 Typical Junction Capacitance**



**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



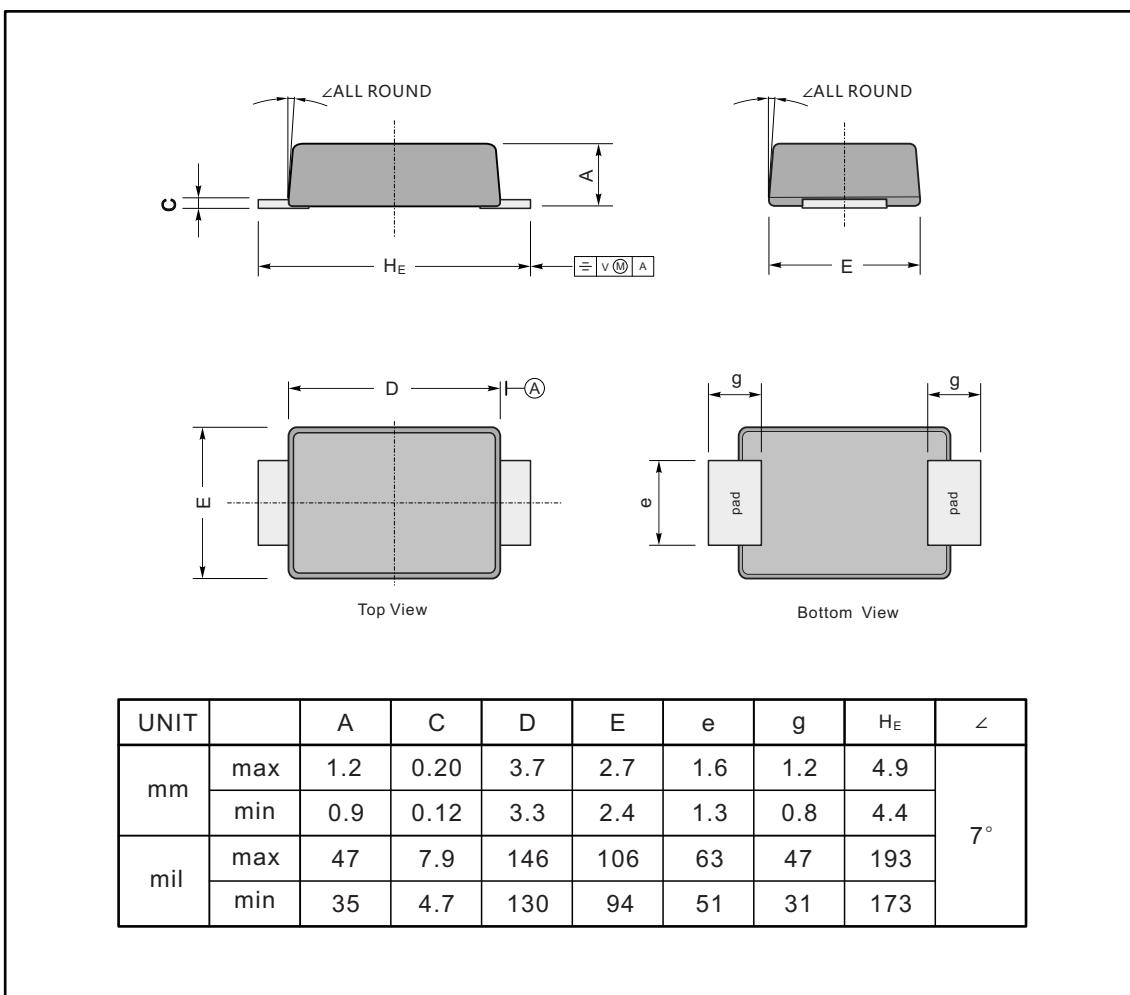
**Fig.6 Typical Transient Thermal Impedance**



## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMAF



The recommended mounting pad size

